

Company Name:	OAo Limited
Posting Date:	20 June 2024
Category:	ITC STEM Internship Scheme
Company Overview:	OAo Limited is an innovative IT company specializing in providing AI solutions for 3D space. We are currently focusing on enhancing our 3D anatomy platform, GIMII, which leverages cutting-edge AI technologies to deliver fast, accurate, and immersive 3D scanning and visualization experiences. As part of our continuous growth, we are looking for a talented and motivated AI Research Intern to join our team and contribute to our exciting projects.
Company Website:	www.oaohk.com
Position/Title:	AI Research Intern
No. of vacancy(ies):	2
Proposed Internship Duration:	59 days
Job Description & Requirements:	<p>Job Description:</p> <ul style="list-style-type: none"> • We are seeking an AI Research Intern with a passion for 3D model reconstruction and alignment. • The ideal candidate will have a strong background in computer science, artificial intelligence, and experience with 3D modeling technologies. • This internship offers a unique opportunity to work on real-world projects that push the boundaries of AI in 3D applications. Job Summary: - 3D Model Reconstruction: Assist in developing and improving algorithms for 3D model reconstruction from multiple images and datasets. • Image Alignment: Work on techniques for accurate alignment and registration of 3D models to ensure high precision and consistency. • AI Integration: Integrate AI and machine learning techniques to enhance the performance and accuracy of 3D reconstruction processes. • Research and Development: Conduct research on the latest advancements in AI, machine learning, and 3D modeling to continuously improve our technology. <p>Job Requirements:</p> <ul style="list-style-type: none"> • Currently pursuing or recently completed a Bachelor's degree in Computer Science, Artificial Intelligence, Engineering, or a related field • Proficiency in programming languages such as Python. Experience with AI frameworks (e.g., TensorFlow, PyTorch) and 3D modeling software (e.g., Blender, Maya). • Strong skills in 3D space calculation, including knowledge of 3D geometry, transformations, and coordinate systems. • Familiarity with tools and libraries such as OpenCV, PCL (Point Cloud Library), and photogrammetry software is a plus. • Demonstrate problem-solving skills through innovation, hypothesizing, design, and implementation analytically and quantitatively. • Good communication and interpersonal skills. • Self-motivated, willing to learn.
Internship Period:	<p>Summer Term 2024</p> <p>Full-time placements with a duration of no less than 4 consecutive weeks (28 calendar days)</p>
How to Apply:	Please read the application guidelines to ensure that you could fulfill the scheme requirements prior to applying for the intern(s).

	<p>Interested students should submit your application directly to the employer with your CV at your earliest convenience.</p> <p>Email to recruit@oaohk.com</p> <p>Application Deadline: 28/6/2024</p>
Salary / Hourly Rate:	<p>HK\$11,190 per month, capped at three months (i.e. 90 days, maximum at HK\$33,570) in one academic year under ITC STEM Internship Scheme</p> <p>For Summer 2024 Internships, the allowance is estimated to be disbursed in December 2024.</p>
Once confirm the internship offer:	<p>Student interns who confirm the internship offer are required to*:</p> <ol style="list-style-type: none"> (1) submit declaration form which is available on SDSC's website before the commencement of internship; (2) declare as “Student Interns” or “Work Experience Students” if applicable for exemption of minimum wage requirement before the commencement of internship; (3) report to SDSC via online registration form with supporting document(s) before the commencement of internship; (4) submit the duly completed Assessment/Evaluation Form to SDSC for processing the allowance upon completion of the whole internship period or the submission deadline, whichever is earlier. <p><i>*Details please refer to the email “Internship - Guidelines and Procedures (Summer Term 2024)” sent on 17 May 2024</i></p>